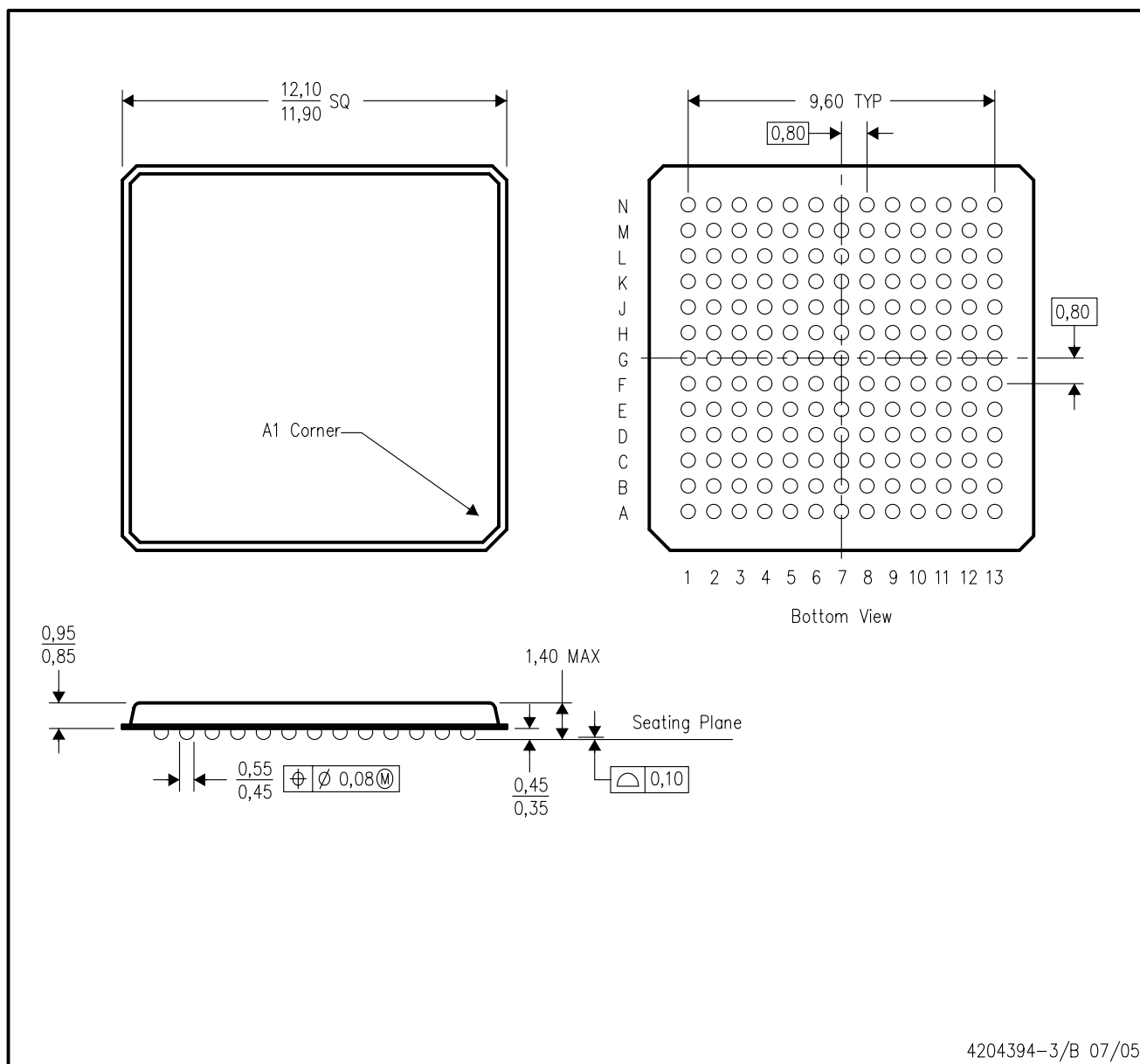


ZGU (S-PBGA-N169)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Micro Star BGA configuration
 - D. This is a lead-free solder ball design.

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